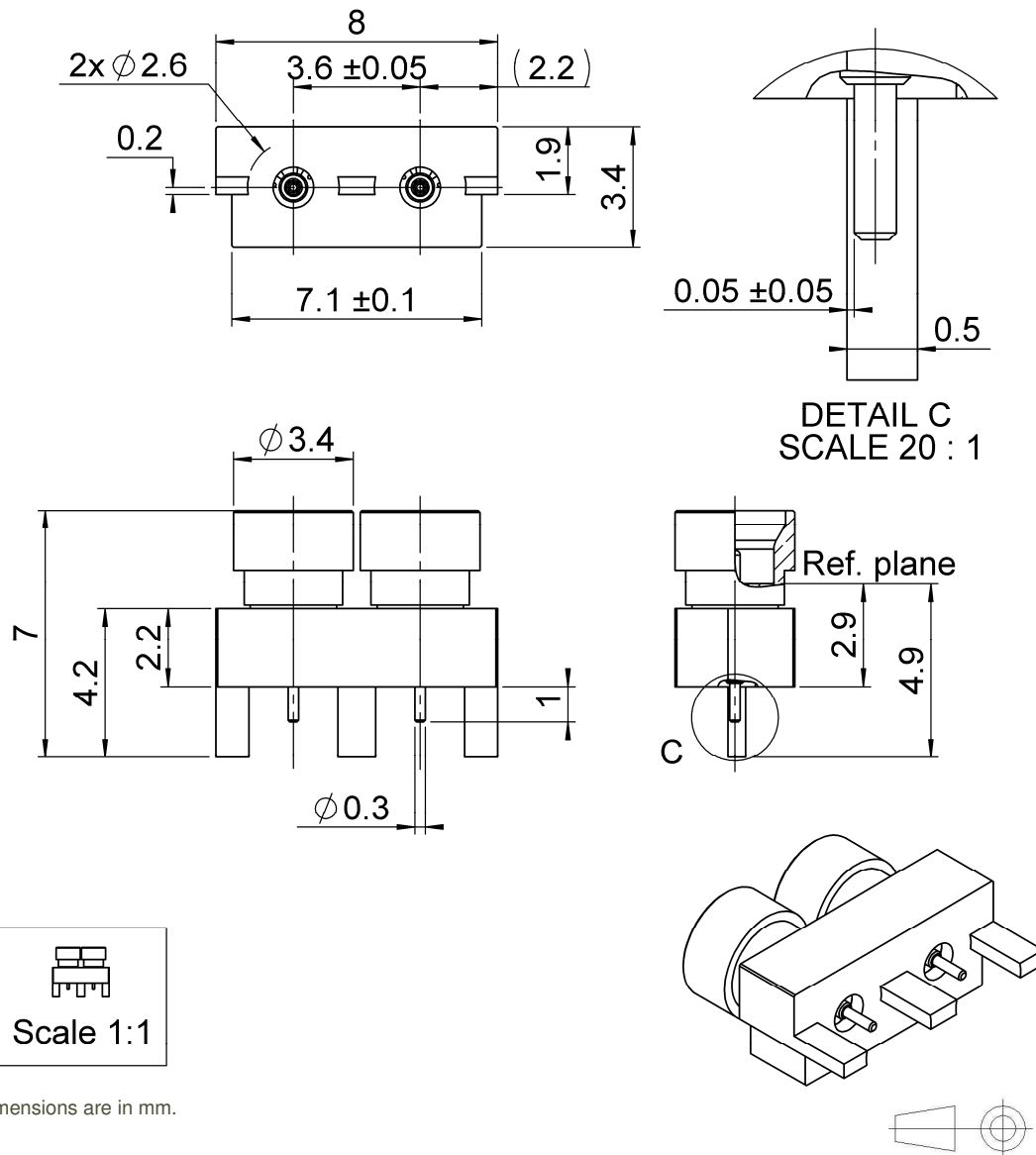


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ISSUE 1450A

SERIES **SMPM**

PART NUMBER **R201423700**



COMPONENTS	MATERIALS	PLATING (µm)
Body	BRASS	NPGR
Center contact	BERYLLIUM COPPER	NPGR
Outer contact		
Insulator	PEEK	
Gasket		
Others parts		
-	-	-
-	-	-

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ISSUE **1450A**

SERIES **SMPM**

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PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-65	GHz
VSWR	0.0000	x F(GHz) Maxi
Insertion loss	0.1	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	NA	- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini
Center contact resistance	6	m Ω Maxi
Outer contact resistance	2	m Ω Maxi

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	7	N mini
Axial force – Opposite end	7	N mini
Torque	NA	N.cm mini
Mating force		
Engagement force - smooth bore	18	N Maxi
Disengagement force - smooth bore	7	N mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	500	Cycles mini
Weight	0.6200	g

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

HUAWEI 14040556 V7.0

OTHER CHARACTERISTICS

Assembly instruction: **NA**

Others:

* Coaxial transmission line only

* VSWR: ≤ 1.05 , DC to 15GHz

≤ 1.15 , 15GHz to 25GHz

≤ 1.22 , 25GHz to 40GHz

*VSWR in application depends decisive on PCB layout

Vibration: MIL-STD-202, Method 204, Condition A

Shock: MIL-STD-202, Method 213, Condition A

Salt Spray: MIL-STD-202, Method 101, Condition B, 48h

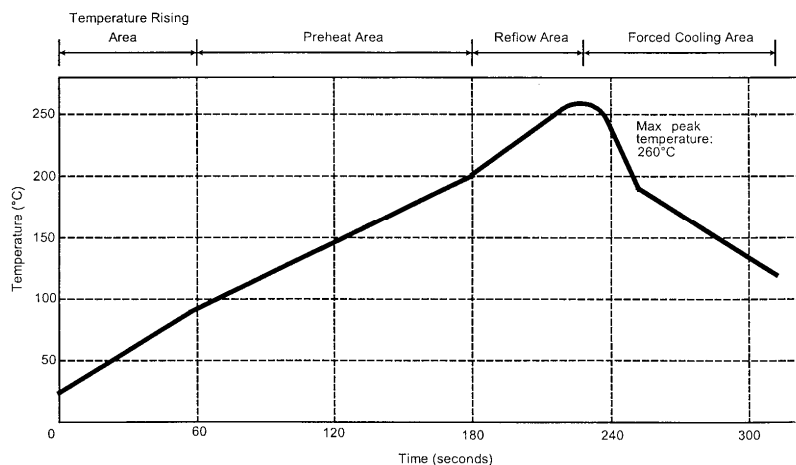
Humidity-Temperature Cycling: MIL-STD-202, Method 106

Thermal Shock: MIL-STD-202, Method 107, Condition B

SOLDER PROCEDURE

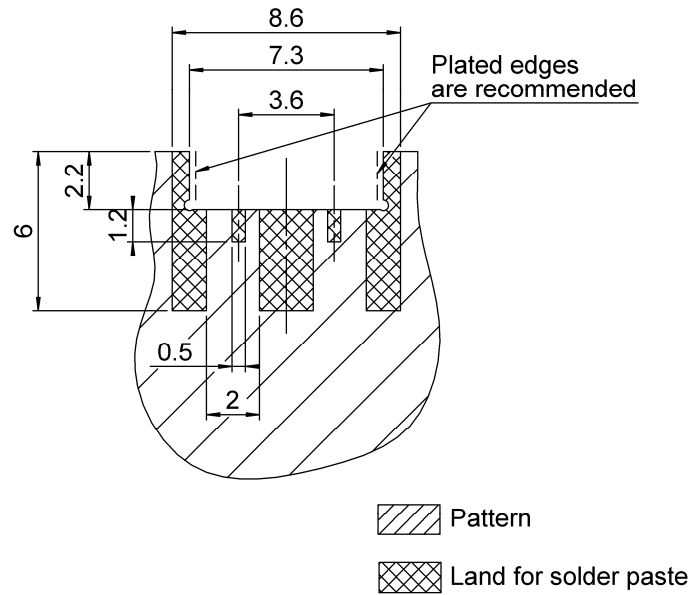
- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 microns (5.9 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.
Below, please find the typical profile to use.
- Cleaning of printed circuit boards.
- Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



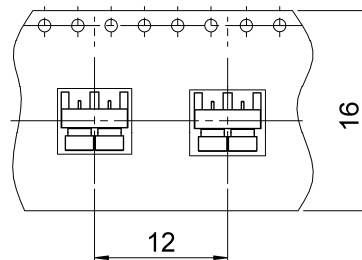
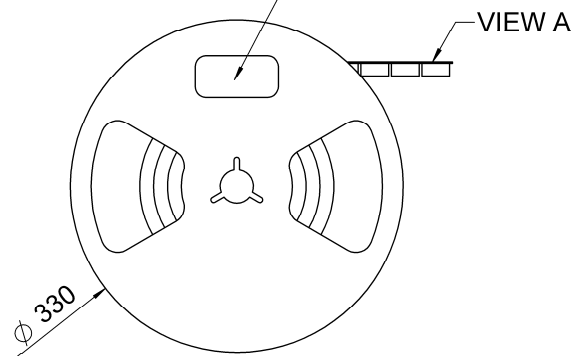
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260 °C	10	sec
Min dwell time @235 °C	20	sec
Max dwell time @235 °C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100 °C	420	sec

Recommended PCB Mount



Packaging

PLACE RESERVED FOR LABEL



VIEW A